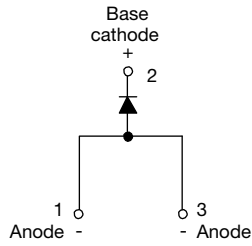


## Surface Mount Fast Soft Recovery Rectifier Diode, 10 A


 TO-263AB (D<sup>2</sup>PAK)


### FEATURES

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

### APPLICATIONS

- Output rectification and freewheeling in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

### DESCRIPTION

The VS-10ETF..S-M3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRODUCT SUMMARY	
Package	TO-263AB (D <sup>2</sup> PAK)
I <sub>F(AV)</sub>	10 A
V <sub>R</sub>	1000 V, 1200 V
V <sub>F</sub> at I <sub>F</sub>	1.33 V
I <sub>FSM</sub>	155 A
t <sub>rr</sub>	80 ns
T <sub>J</sub> max.	150 °C
Diode variation	Single die
Snap factor	0.6

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
I <sub>F(AV)</sub>	Sinusoidal waveform	10	A
V <sub>R(RM)</sub>		1000/1200	V
I <sub>FSM</sub>		155	A
V <sub>F</sub>	10 A, T <sub>J</sub> = 25 °C	1.33	V
t <sub>rr</sub>	1 A, 100 A/μs	80	ns
T <sub>J</sub>	Range	-40 to +150	°C

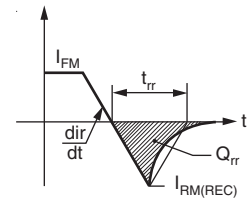
VOLTAGE RATINGS			
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA
VS-10ETF10S-M3	1000	1100	4
VS-10ETF12S-M3	1200	1300	

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 125 °C, 180° conduction half sine wave	10	A
Maximum peak one cycle non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, rated V <sub>RRM</sub> applied	130	
		10 ms sine pulse, no voltage reapplied	155	
Maximum I <sup>2</sup> t for fusing	I <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	85	A <sup>2</sup> s
		10 ms sine pulse, no voltage reapplied	120	
Maximum I <sup>2</sup> √t for fusing	I <sup>2</sup> √t	t = 0.1 ms to 10 ms, no voltage reapplied	1200	A <sup>2</sup> √s



ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	$V_{FM}$	10 A, $T_J = 25\text{ }^\circ\text{C}$		1.33	V
Forward slope resistance	$r_t$	$T_J = 150\text{ }^\circ\text{C}$		22.9	$m\Omega$
Threshold voltage	$V_{F(TO)}$			0.96	V
Maximum reverse leakage current	$I_{RM}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^\circ\text{C}$		4	

RECOVERY CHARACTERISTICS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	$t_{rr}$	$I_F$ at 10 $A_{pk}$ 25 A/ $\mu$ s 25 $^\circ\text{C}$	310	ns
Reverse recovery current	$I_{rr}$		4.7	A
Reverse recovery charge	$Q_{rr}$		1.05	$\mu\text{C}$
Typical snap factor	S		0.6	



THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-40 to +150	$^\circ\text{C}$
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation	1.5	$^\circ\text{C/W}$
Maximum thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		62	
Soldering temperature	$T_S$		260	$^\circ\text{C}$
Approximate weight			2	g
			0.07	oz.
Marking device		Case style D <sup>2</sup> PAK (SMD-220)	10ETF10S	
			10ETF12S	

**Note**

<sup>(1)</sup> When mounted on 1" square (650 mm<sup>2</sup>) PCB of FR-4 or G-10 material 4 oz. (140  $\mu$ m) copper 40  $^\circ\text{C/W}$ . For recommended footprint and soldering techniques refer to application note #AN-994.

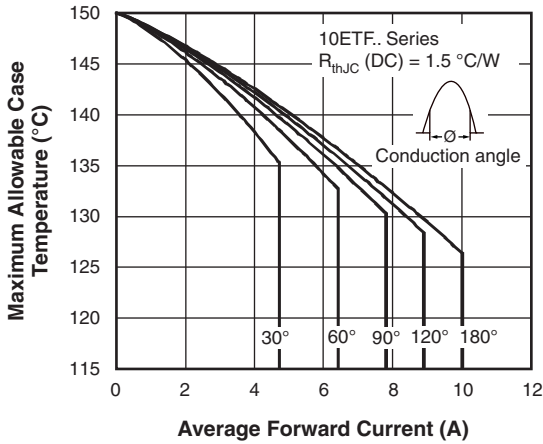


Fig. 1 - Current Rating Characteristics

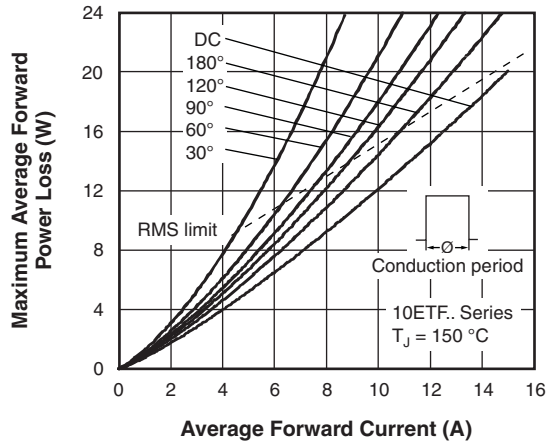


Fig. 4 - Forward Power Loss Characteristics

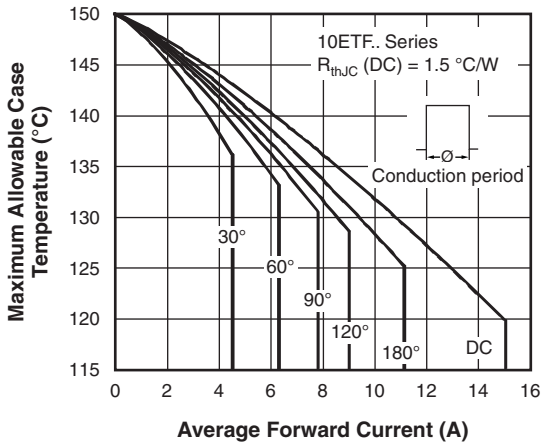


Fig. 2 - Current Rating Characteristics

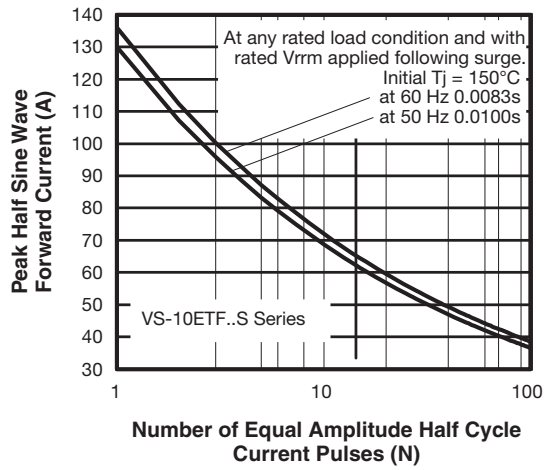


Fig. 5 - Maximum Non-Repetitive Surge Current

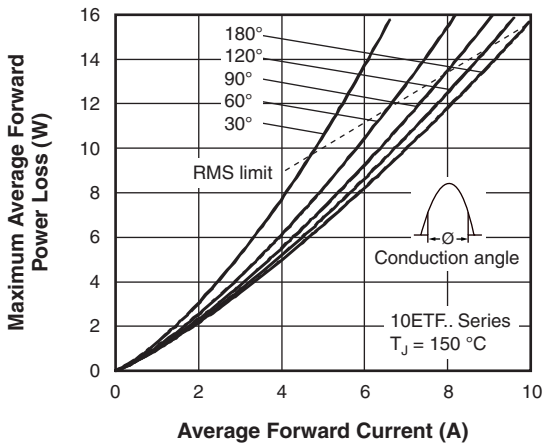


Fig. 3 - Forward Power Loss Characteristics

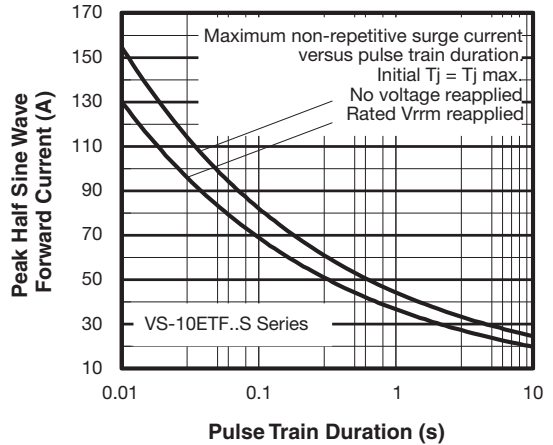


Fig. 6 - Maximum Non-Repetitive Surge Current

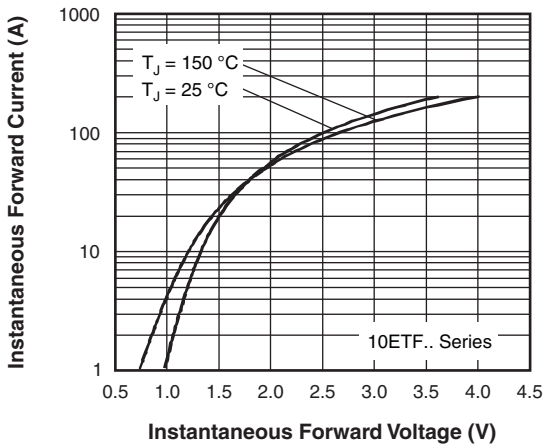


Fig. 7 - Forward Voltage Drop Characteristics

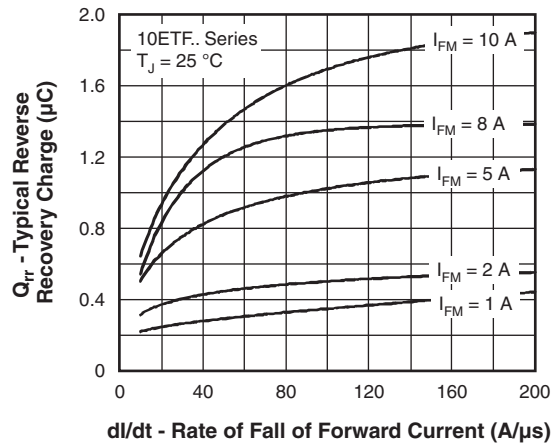


Fig. 10 - Recovery Charge Characteristics,  $T_J = 25\text{ °C}$

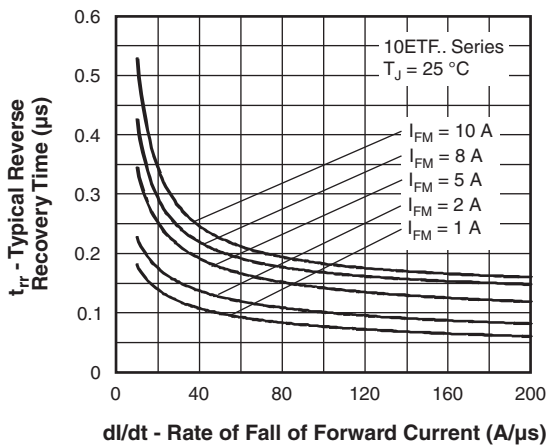


Fig. 8 - Recovery Time Characteristics,  $T_J = 25\text{ °C}$

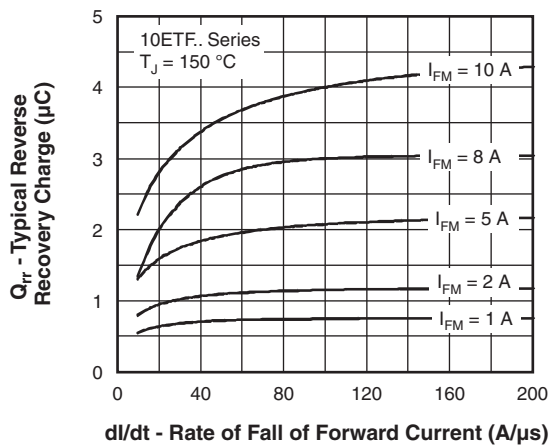


Fig. 11 - Recovery Charge Characteristics,  $T_J = 150\text{ °C}$

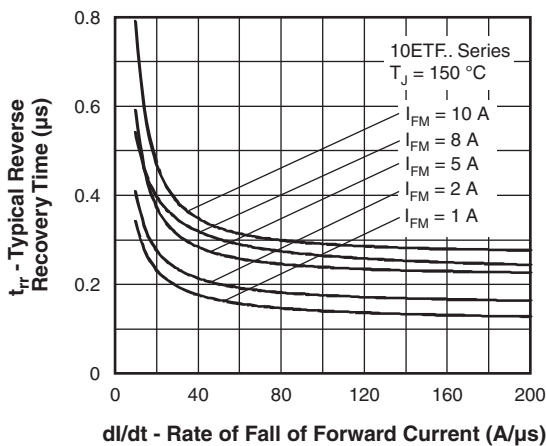


Fig. 9 - Recovery Time Characteristics,  $T_J = 150\text{ °C}$

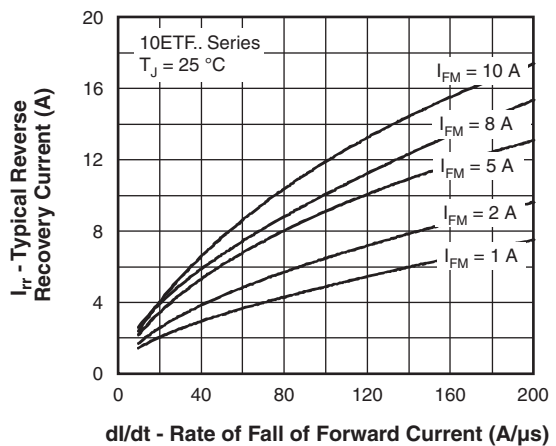


Fig. 12 - Recovery Current Characteristics,  $T_J = 25\text{ °C}$

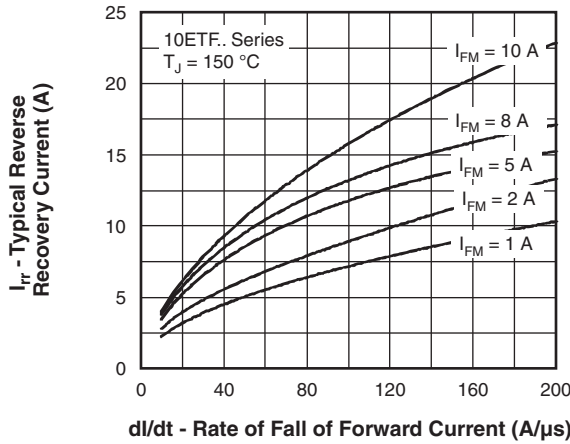


Fig. 13 - Recovery Current Characteristics, T<sub>J</sub> = 150 °C

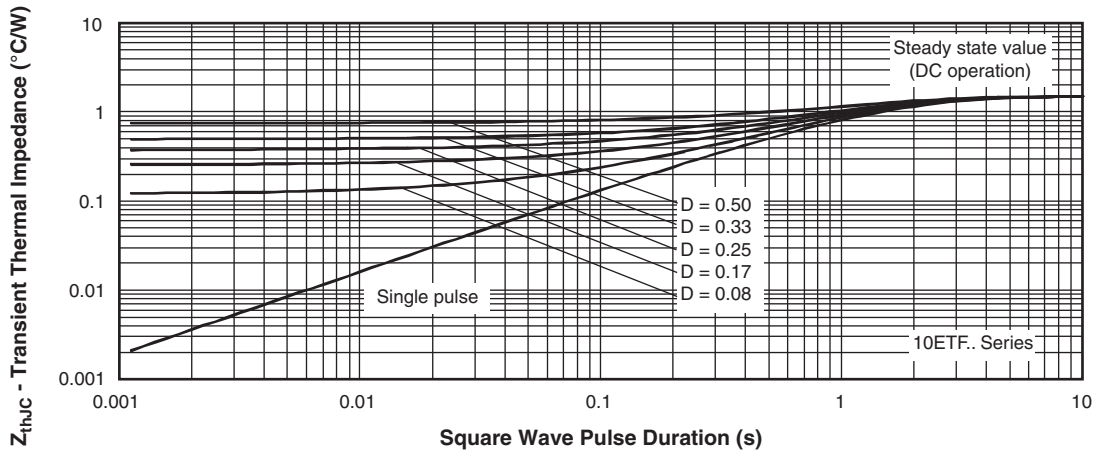
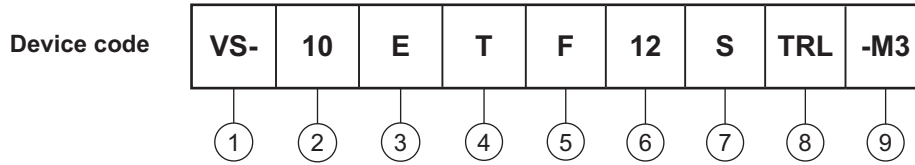


Fig. 14 - Thermal Impedance Z<sub>thJC</sub> Characteristics



## ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (10 = 10 A)
- 3** - Circuit configuration:  
E = single diode
- 4** - Package:  
T = D<sup>2</sup>PAK
- 5** - Type of silicon:  
F = fast soft recovery rectifier
- 6** - Voltage code x 100 = V<sub>RRM</sub> ——— 

10 = 1000 V
12 = 1200 V
- 7** - S = surface mountable
- 8** -
  - None = tube
  - TRR = tape and reel (right oriented)
  - TRL = tape and reel (left oriented)
- 9** - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10ETF10S-M3	50	1000	Antistatic plastic tubes
VS-10ETF10STRR-M3	800	800	13" diameter reel
VS-10ETF10STRL-M3	800	800	13" diameter reel
VS-10ETF12S-M3	50	1000	Antistatic plastic tubes
VS-10ETF12STRR-M3	800	800	13" diameter reel
VS-10ETF12STRL-M3	800	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95046">www.vishay.com/doc?95046</a>
Part marking information	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
Packaging information	<a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a>

## D<sup>2</sup>PAK

### DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

#### Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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